

DATE DIV/SEC

PROCESS TYPE

SUBGROUP

CONTACT (S)

GROUP

SURVEYOR (S)

LOCATION

JOB CLASSES

NUMBER OF EMPLOYEES

GENERAL PROCESS DESCRIPTION

HAZARD

- (Check all that apply) Noise Vibration Non-ionizing Radiation Cleaners Insulation Glues Paints Metals Dusts Fumes Mists
 Gases Vapors Cryogenes Solvents Acids Bases Temp Extremes Magnetic Fields Biological Ergonomics

DATA

- Carcinogens Other

CONTROLS

RECOMMENDATIONS

Instructions:

1. Prepare for the IH Survey:

- a) Define the scope of the survey.
- b) Review past IH monitoring results, audits, field notes, Tripartites, etc.
- c) Contact supervisor, Building Manager of the survey area and arrange meeting time.

2. Perform the IH Assessment:

- a) Meet designated contact. Discuss process (including non-routine operations).
- b) Interview employees. Discuss process and potential exposures.
- c) Conduct any prompt, confirmatory monitoring (direct reading instrument, SLM).
- d) Complete field notes on Industrial Hygiene Assessment Form (IHAF):
 - 1) HAZARD - List each particular hazard of concern,
 - 2) DATA - List any specific information regarding hazard exposure (frequency, duration, number of employees affected, process, etc.),
 - 3) CONTROLS - List controls presently in place (ventilation, PPE, administrative),
 - 4) RECOMMENDATIONS - Determine potential exposures and recommend possible IH management strategies (periodic monitoring, training needs, PPE requirements, additional controls, etc.).

3. Enter IH Assessment Data

- a) Access and log into the IH Assessment Database at http://www-esh.fnal.gov/pls/default/web_forms.apps?name=HS .
- b) Enter the information in the top-left section of the form. A unique ID number will be generated when this section is complete.
- c) Continue to enter data into each field. Note that several Process Types and Hazards can be entered from the pull-down lists. For each Hazard entered, corresponding data must be entered into the Hazard Data section (Controls, Data, Recommendations, Standards).

Potential Hazards:*Physical:***Noise** (continuous, impact), **Vibration**, **Non-Ionizing Radiation** (microwave, RF, IR, lasers)*Chemical (inhalation):***Metals** (Pb, Be, Cu, Al, Cr, Ni, etc.), **Dusts** (nuisance, silica, asbestos, etc.), **Mists** (spray Inhalation painting, fluxes), Fumes (welding, brazing, torch cutting), Cryogenics (oxygen deficiency), Solvents (acetone, halogenated), Acids (HCl, H₂SO₄), Bases (NaOH),*Chemical (dermal):***Cleaners** (detergents, acids, caustics), **Insulation** (fiberglass), **Glues** (epoxies), **Paints** (solvents)*Biological:***BBP, TB, Mold, Fungi, Bacteria***Other:***Heat Stress, Cold Stress, Magnetic Fields, Ergonomic**